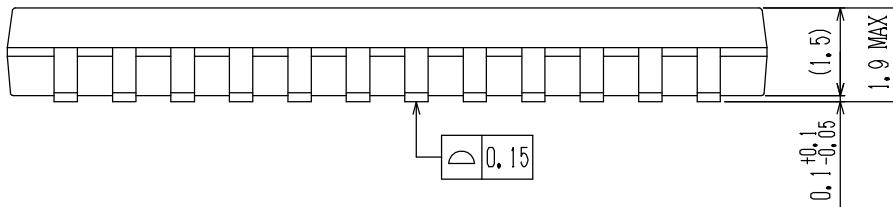
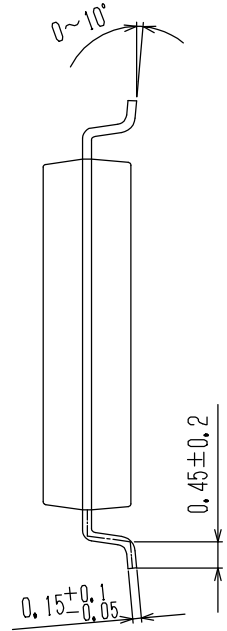
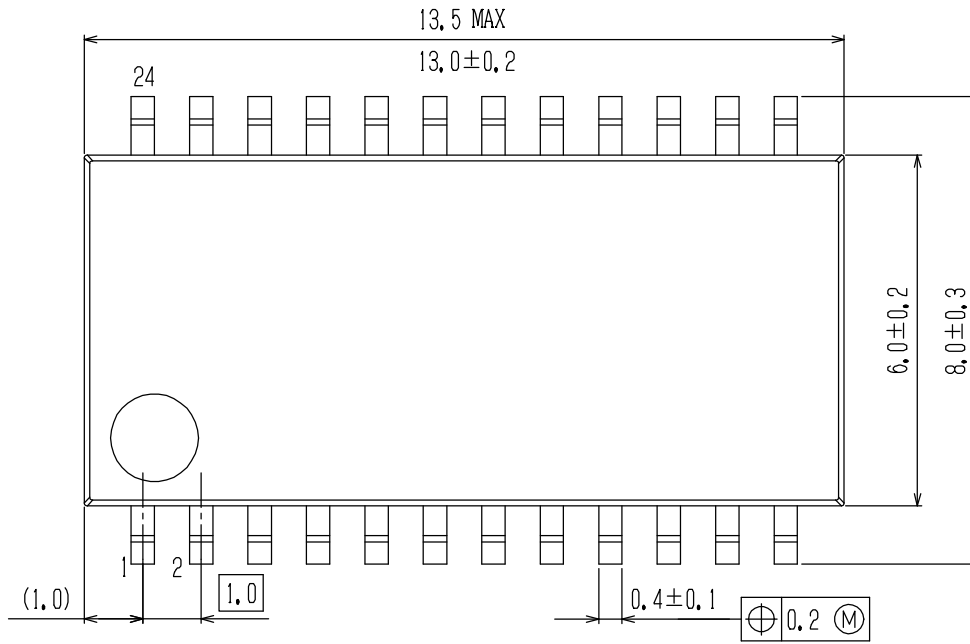
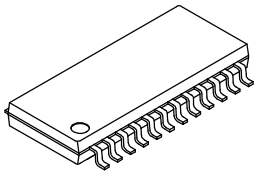


**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

SOIC24W / MFP24SJ (300 mil)  
CASE 751DB  
ISSUE O

DATE 31 MAY 2012



<b>DOCUMENT NUMBER:</b>	<b>98AON80820E</b>	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SOIC24W / MFP24SJ (300 MIL)</b>	<b>PAGE 1 OF 2</b>

